



Dear Valued Customer

Doc. No.: 2223009
Issue date: September 1, 2023

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Notification of Product/Process Change

This is an announcement of change(s) to the process of the products currently supplied by ROHM Co., Ltd.

We request your acknowledgement of the receipt of this notification within the given period.

Please provide your your reply by March 31, 2024

Title of change	SiC 3G SBD TO-220FM: 6inch Wafer introduction, Wafer (to Miyazaki) and PKG factory (to GEM) change	
Affected product(s)	Manufacturer part number	Customer part number
	SCS3□□AMC	Please see email details
Detailed description of change	Before	After
	SiC wafer diameter: 4inch (ROHM APOLLO Co., Ltd. Chikugo plant) Package: TO-220FM (SP Semiconductor & Communication Co., Ltd. [KOREA]) P/Ns: SCS3□□AMC	SiC wafer diameter: 6inch (LAPIS Semiconductor Co., Ltd. Miyazaki plant) Package: TO-220FM-2LGE (GEM Electronics (Hefei) Co., Ltd. [CHINA]) P/Ns: SCS3□□AMC7G
Reason for change	- To increase production output by enhancing productivity and efficiency - End of production of 4-inch SiC wafers due to the transition to 6inch SiC wafers (The conventional PN's will be ended their productions after transition to new PN's.)	
Anticipated impact on quality	There is no difference in reliability and electrical characteristics.	
Identification of change	P/N(Marking), Appearance	
Planned first ship date : April 1, 2024		Sample available schedule : September 1, 2023
Comments		

		Reply date				
Customer reply	<input type="checkbox"/> 1. Approved. <input type="checkbox"/> 2. Accepted with conditions.					
Condition for approval / reason for rejection						
Comments						
Customer company name						
Customer signature		Department				
Customer signature		Department				